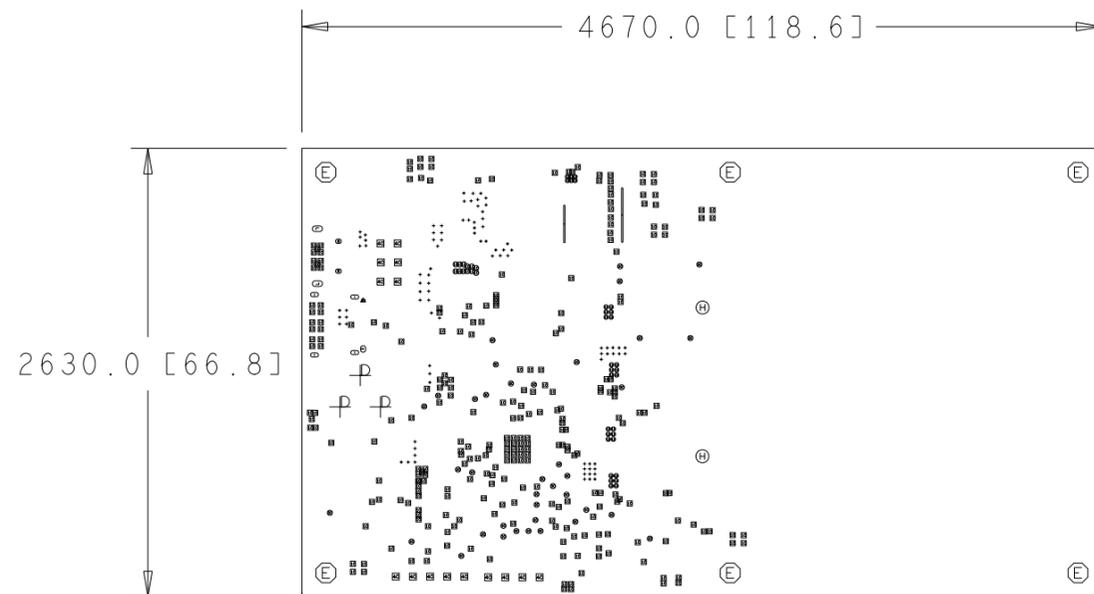


STACK UP DETAILS:

TOP - 10Z
L1 - 10Z
L2 - 10Z
BOTTOM - 10Z

BOARD DIMENSIONS ARE IN INCH[MM]



NOTES :

- 1) FABRICATE BOARD PER IPC-A-600G
- 2) MATERIAL FR4 4 LAYER BOARD.
- 3) BOARD THICKNESS : 0.062" +/-0.006".
- 4) MINIMUM PLATING IN ALL THE THROUGH HOLE SHALL BE 0.001 INCH Cu.
- 5) ALL HOLES ARE PLATED THROUGH UNLESS OTHERWISE SPECIFIED.
- 6) HOLE SIZE ARE FINISHED SIZE.
- 7) SOLDER MASK BOTH SIDE WITH GREEN LIQUID PHOTO IMAGABLE.
- 8) FOR LAYER BUILD UP SEE STACK UP DETAIL.
- 9) SILKSCREEN BOTH SIDE "WHITE EPOXY" OVER SOLDER MASK
- 10) DEBURR ALL SHARP EDGES
- 11) BOW AND TWIST: SHOULD NOT EXCEED 0.007" PER INCH.
- 12) PLATED PADS ON TOP AND BOTTOM MUST BE SAME HEIGHT AS CONDUCTOR PAD AND TRACE
- 13) PLATING: IMMERSION GOLD FINISH.
- 14) NO VENDOR LOGO OR NAME ON THE BOARD.
- 15) BOARD MUST BE ROHS COMPLAINT.
- 16) CLIP SILKSCREEN ON NO MASK AREA.

DRILL CHART: L1 to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	FINISHED_SIZE	ROTATION	TOLERANCE_DRILL	TOLERANCE_TRAVEL	PLATED	QTY
•	10.0	-	+3.0/-3.0	-	PLATED	12

DRILL CHART: TOP to BOTTOM

ALL UNITS ARE IN MILS

FIGURE	FINISHED_SIZE	ROTATION	TOLERANCE_DRILL	TOLERANCE_TRAVEL	PLATED	QTY
▪	10.0	-	+3.0/-3.0	-	PLATED	276
•	12.0	-	+3.0/-3.0	-	PLATED	30
•	20.0	-	+3.0/-3.0	-	PLATED	88
•	30.0	-	+3.0/-3.0	-	PLATED	38
▪	40.0	-	+3.0/-3.0	-	PLATED	15
⊕	125.98	-	+3.0/-3.0	-	PLATED	3
⊕	157.48	-	+4.0/-4.0	-	PLATED	2
•	30.0	-	+3.0/-3.0	-	NON-PLATED	1
⊕	135.0	-	+2.0/-2.0	-	NON-PLATED	6
•	33.461x25.591	0.000	+3.0/-3.0	+3.0/-3.0	PLATED	2
•	46.0x24.0	0.000	+3.0/-3.0	+0.0/-0.0	PLATED	4
•	59.059x32.48	0.000	+3.0/-3.0	+3.0/-3.0	PLATED	2
•	38.0x30.0	90.000	+3.0/-3.0	+0.0/-0.0	NON-PLATED	1
	220.0x8.0	90.000	+2.0/-2.0	+0.0/-0.0	NON-PLATED	1
	320.0x8.0	90.000	+2.0/-2.0	+0.0/-0.0	NON-PLATED	1